PATENT APPLICATION

#### 03500.016072.1

6	E Vo	IN THE UNITED STATES PA	TENT A	AND TRADEMARK OFFICE
DEC	3 0 5004	다. 도		
<b>\ a</b> .	In re A	bplication of:	)	
TIE!	Le THYOR		:	Examiner: L. Pham
	MINEC	SHIMOTSUSA, ET AL.	)	
			:	Group Art Unit: 2814
Application No.: 10/657,269			)	
			:	
	Filed: S	September 9, 2003	)	
		•	:	
	For:	SEMICONDUCTOR DEVICE,	)	
		METHOD FOR	:	
		MANUFACTURING THE	)	
		SAME, AND LIQUID JET	:	
		APPARATUS	)	December 29, 2004

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

#### **LETTER**

Sir:

Enclosed is a copy of an Official Action dated September 24, 2004, which issued in a Chinese application corresponding to the above-referenced application. An English-language translation of the Chinese Official Action is also enclosed.

The documents cited in the Chinese Official Action were previously cited in the September 8, 2003 Information Disclosure Statement and/or the April 13, 2004 Information Disclosure Statement.

Favorable consideration is earnestly solicited.

Applicants' undersigned attorney may be reached in our Costa Mesa,

California office at (714) 540-8700. All correspondence should continue to be directed to our below-listed address.

Respectfully submitted,

Damond E. Vadnais Attorney for Applicants Registration No.: 52,310

FITZPATRICK, CELLA, HARPER & SCINTO 30 Rockefeller Plaza
New York, New York 10112-3800

Facsimile: (212) 218-2200

CA\_MAIN 90164v1

## THE PATENT OFFICE OF THE PEOPLE'S REPUBLIC OF CHINA

Address: 6 Xi Tu Cheng Lu, Haidian, Beijing Post Code: 100088

Applicant:	CANON KABUSHIKI KAISHA		
Attorney:	WANG YIPING	Date of Notification:	
Application No.:	01145787.2	Dute: 24 Month: 09 Year: 2004	
Title of the Invention:	SEMICONDUCTOR DEVICE, METHOD THE SAME, AND LIQUID JE		

#### Notification of the First Office Action

	above-id People's The Chine	entified pa Republic	atent app of China Office h	mination as to subs lication for invention (hereinafter referred as decided to exami	on under Artic d to as "the Pa	ilc 35(1) of atent Law")	the Pater	it Law of the	
2.5	The applic	ant claime	cd priorit	y/priorities based o	n the applicat	ion(s):			
	filed in	<u>JP</u>	on	Dec. 28, 2000	_, filed in	JP	on _	Feb. 9, 20	01
	m Dain	J.F	on	Feb. 9, 2001	_, filed in	JP	ОЛ	Fcb. 9, 20	01 .
	filed in		on	the priority docume	_, filed in		on		,
3. i 3. i	The application of the amendation of the amendat	plication( under Ar under Ar ation is a ant submit led led amendmer	not provi (s) was/w ticle 30 o PCT con tted amen	ided the priority dere filed and there of the Patent Law. tinuation.  dments to the applied submitted of submitted of temply with	eation onononononof the late of the in	ity claim(s)	and on and are not a aw.	acceptable,	have, wherein
p p	Examination Examin	on as to si of the desc of the desc of the desc	abstance cription, c cription, c cription, c	was directed to the was directed to the claims and p claims and p claims and p	documents as ages o ages o ages o	s specified he fithe drawing the drawing fithe drawing fit	oelow: ngs subm ngs subm ngs subm	uitted on	
5. E	This Noting	fication is	issued w	ithout search reportith consideration of document(s) cited	f the search re		ic referei	nce ոսախcr(s	) will

be used throughout the examination procedure):

No.	Number(s) or Title(s) of Reference(s)  8 -97410	Date of Publication (or the filing date of conflicting application)
1	<b>頂平8-97401A</b> ~ ★ @	Date: 12 Month: 04 Year: 1996
2	JP Ψ 6-69497A ~ 米②	Date: 11 Month: 03 Year: 1994
3		Date: Month: Year:

	•		
6. Conclusions of the Actio	on:		
☑ On the Specification:			
☐ The subject matter	contained in the app	plication is not patenta	ble under Article 5 of the Patent Law.
☐ The description doe	is not comply with	Article 26 paragraph 3	of the Patent Law.
☑ On the Claims:	cription does not co	omply with Rule 18 of	the Implementing Regulations.
Claim(s) is/z	ire not natentable in	adar Articla 25 of the 1	Detent T
Claim(s) doe	es/do not comply w	th the definition of in-	ventions prescribed by Rule 2
paragraph I of the I	mplementing Regul	ations	vendons presented by Rule 2
Claim(s) doe	s/do not possess the	c novelty as required l	by Article 22 paragraph 2 of the Patent
Law.			
☑ Claim(s) 1-6,10,13-	16 does/do not pos	sess the inventiveness	as required by Article 22 paragraph 3
of the Patent Law.			
Claim(s) doc	s/do not possess the	e practical applicabilit	y as required by Article 22 paragraph
4 of the Patent Law.			•
⊠ Claim(s) _51_ doc	s/do not comply wi	th Article 26 paragrap	h 4 of the Patent Law.
Claim(s) doe	s/do not comply wi	th Article 31 paragrap	oh Fof the Patent Law.
the Implementing R	<u>-20,22-20,31-30,33</u>	40 does/do not comp	ly with the provisions of Rule 20 of
⊠ Claim(s) 27 doe	sguanons. s/do not comply wi	th the provisions of R	ule 21 of the Implementing
Regulations.	man not comply wi	ar are provisions or ic	are 21 of the implementing
Claim(s) doc	s/do not comply wi	th Article 9 of the Pate	ent Law.
☐ Claim(s) doe	s/do not comply wi	th the provisions of R	ule 12 paragraph 1 of the
Implementing Regul	ations.	-	
7 to sie o Cale o 1			
7. In view of the conclusion	is set forth above, t	he Examiner is of the	opinion that:
The applicant should	make amenoments	as directed in the text	portion of the Notification. ne application is parentable and make
amendments to the	innlication where th	ponse reasons why u	s pointed out in the text portion of the
Notification, otherw	ise, the application	will not be allowed	s pointed out in the text portion of the
☐ The application cont	ains no allowable	invention, and there	fore, if the applicant fails to submit
sufficient reasons to	prove that the appli	cation does have meri	its, it will be rejected.
8. The followings should be	taken into conside	ration by the applican	t in making the response:
(1) Under Article 37 of	the Patent Law, the	he applicant should r	respond to the office action within 4
months counting from	the date of receip	ot of the Notification.	. If, without any justified reason, the
time limit is not met, t			
			th the provisions of Article 33 of the format of the substitution should be in
conformity with the re			
(3) The response to the	Notification and/or	revision of the applic	cation should be mailed to or handed
over to the "Reception	Division" of the	Patent Office, and doc	tuments not mailed or handed over to
the Reception Division	ns have no legal cit	ect.	
	ent, the applicant as	nd/or his agent shall n	ot interview with the Examiner in the
Patent Office.			
9. This Notification contain	s a text portion of	4 pages and the foll	lowing attachments:
	, whiting <u>24</u> pages.	. LJ	
Examination Deer 3	Examiner:	ZHONG Vi	Sent of the Examination Departmen

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## Chinese Examiner's Comment

### Text of the First Office Action

As stated in the specification, the present application relates to a semiconductor device, method for manufacturing the same and liquid jet application. After examination, the Examiner's comments are as follows.

- 1. Claim 1 is not in conformity with Rule 20, 1 of the Implementing Regulations. Word of "the surface side" is an unclear wording, which makes the scope for protection is not clear, since it does not clearly describe its concrete position. Wording of "gate electrodes formed...with a gate insulator film put between them" does not clearly describe that the insulating film is formed between each other of plural gate electrodes, or formed between the gate electrodes and the gate insulator film, so as to make the scope for protection unclear. According to the contents of the specification, it should be changed to "a gate insulator film is arranged between these gate electrodes and the channel region". Claim 1 does not clearly describe positional relation and connection of the electro-thermal conversion elements and the switching devices so that the structure of the claimed semiconductor device is not clear.
- 2. Even though the present claim 1 is amended based on the above comments, it is still not in conformity with provision of Article 22, 3 of the Patent Law. Reference 1 (JPhei8-897410A, whole specification and figs. 1~8) discloses a method for manufacturing transverse DMOS, wherein the DMOS comprising a n-type semiconductor region 14 formed on a p-type substrate 12; insulating film 28; gate electrode 26; p-type semiconductor region 20; source 16 formed on said p-type semiconductor region, drain 18 formed on said n-type semiconductor region, and said p-type semiconductor region is formed between plural drains. The present claim 1 is different of from Reference 1 in that: the plurality of electro-thermal conversion elements and the plurality of switching devices are integrated on the p-type substrate; the p-type semiconductor region has an impurity concentration higher than that of the n-type semiconductor region. Reference 2 (JPhei6-69497A, whole specification and figs. 1~22) discloses a structure where an electro-thermal conversion device drives semiconductor device, wherein a plurality electro-thermal conversion devices and a plurality of switching devices are integrated on a p-type substrate. And it is a conditional measure and belongs to well-known knowledge for persons in the art, to arrange impurity concentration of the drain lower than that of channel region, and/or to make the drain more deep so as to improve breakdown voltage to become higher. Further, references 1 and 2 are in the same technical field, It needs no inventive work for a person skilled in the art to apply the structure of the transistor of reference 1 to the semiconductor device of reference 2 in connection with the well-known knowledge to obtain the technical solution of the present. Therefore, claim 1 does not



possess inventiveness.

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- 3. Claim 2 is not in conformity with provision of Article 22, 3 of the Patent Law. Reference 1 has disclosed the additional technical feature of the present claim 2(see figs.). Therefore, claim 2 does not possess inventiveness.
- 4. Claims 3-6, 10, 13-16 are not in conformity with provision of Article 22, 3 of the Patent Law. References 1 and 2 have disclosed all additional technical features of claims 3, 5, 6, 10 and 13-16(see figs.), therefore, claims 3, 5, 6, 10, 13-16 do not possess inventiveness. And it is a general connection in the art that electro-thermal conversion elements are connected to a drain. Therefore, claim 4 does not possess inventiveness.
- 5. Claim 5 is not in conformity with Rule 20, 1 of the Implementing Regulations.(This part relates to literal defect, which we shall remove without your instructions.)
- 6. Claims 10, 11 are not in conformity with Rule 20, 1 of the Implementing Regulations. Wording of "drain sides of ..." does not clearly describe the position so that the scope for protection is unclear, which should be amended as "portion near drain of ...".
- 7. Claim 17 is not in conformity with Rule 20, 1 of the Implementing Regulations. Wording of "said drain sides of ..." does exist in its referred claim 1 or 2. Further, the "drain sides" cannot clearly describe the concrete position so as to make the scope for protection unclear. It may be amended to "portion near said drain...". In addition, wording of "... on insulator films thicker than said gate insulator film" is not in its referred claim 1 or 2, and concrete position of the thicker films is not described, so the scope for protection is not clear.
- 8. Claims 18-20 are not in conformity with Rule 20, 1 of the Implementing Regulations. 
  "OFF substrate" is not general term in the art, and can not clearly describe the feature of the substrate. So the scope for protection becomes unclear. Wording of "liquid exhaust portions corresponding to..." does not clearly describe how they are connected, and what is their positional relation.
- 9. Claim 22 is not in conformlty with Rule 20, 1 of the Implementing Regulations. Wording of "surface side..." is unclear, which does not describe concrete potion clearly, so as to make the scope for protection unclear. Feature "doping a first ... by utilizing said gate electrode as a mask" does not clearly describe which position of which layer the impurity is doped, so that the scope for protection is not clear. And feature "forming a semiconductor region by diffusing ..." does not clearly describe the concrete position for forming the semiconductor region, so that the scope for protection is not clear.
- 10. Claim 23 is not in conformity with Rule 20, 1 of the Implementing Regulations. Wording of "surface side..." is unclear, which does not describe concrete potion clearly, so as to make the scope for protection unclear. Feature "doping a first ...by

utilizing said gate electrode as a mask" does not clearly describe which position of which layer the impurity is doped, so that the scope for protection is not clear. And feature "forming a semiconductor region by diffusing ..." does not clearly describe the concrete position for forming the semiconductor region, so that the scope for protection is not clear.

- 11. Claims 24 and 25 are not in conformity with Rule 20, 1 of the Implementing Regulations. Wording of "surface side..." is unclear, which does not describe concrete potion clearly, so as to make the scope for protection unclear. "100KeV or more" is unclear wording so that the scope for protection is unclear, because range of the energy is not clearly defined. Feature of "performing a heat treatment for activating the implanted impurity electrically" does not clearly describe relation between the "impurity" and the "first conductive type ion..." so as to make the scope for protection unclear. The "performing a first conductive type ion implantation into..." should be changed into "performing ion implantation of a first conductive type impurity ...".
- 12. Claim 26 is not in conformity with Rule 20, 1 of the Implementing Regulations. (This part relates to a typing error, which we can correct without your instruction.)

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- 13. Claim 27 is not in conformity with Rule 20, 1 of the Implementing Regulations. Claim 27 is further definition of claim 22, so it should be amended as dependent claim of claim 22.
- 14. Claims 31-34 are not in conformity with Rule 20, 1 of the Implementing Regulations. "OFF substrate" is not general term in the art, and can not clearly describe the feature of the substrate. So the scope for protection becomes unclear. "100KeV or more" is unclear wording so that the scope for protection is unclear, because range of the energy is not clearly defined.
- 15. Claim 35 is not in conformity with Rule 20, 1 of the Implementing Regulations. (The first two points relate to literal defects which we can remove without your instruction.) In addition, the scope for protection is not clear since it is not clearly defined at which position, which region and which layer the second semiconductor region is formed in the whole structure.
- 16 Claim 36 is not in conformity with Rule 20, 1 of the Implementing Regulations. (The comments for claim 36 is exactly the same as that for claim 35, we do not repeat it.)
- 17. Claim 39 is not in conformity with Rule 20, 1 of the Implementing Regulations. (The first point relates to literal defects which we can remove without your instruction.) In addition, the scope for protection is not clear since it is not clearly defined at which position, which region and which layer the second semiconductor region is formed in the whole structure.
- 18. Claim 40 is not in conformity with Rule 20, 1 of the Implementing Regulations. (The

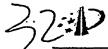
comments for claim 40 is exactly the same as that for claim 39, we do not repeat it.)

19. Claim 51 Is not in conformity with Article 26, 4 of the Patent Law. As described on page 17, par. 3 (corresponding to paragraph bridging over page 52 and page 53 of the Japanese specification) of the specification, and each of embodiments, in order to ensure each of drains can be isolated electrically and respectively, bottom of the second semiconductor region should have sufficiently deep to be connected to the semiconductor substrate which is grounded, so that the second semiconductor region reached to the substrate. If not, the structure is not adapted to an array of transistors of a liquid jet apparatus. However, in the structure of claims 1 and 2 which are referred by claim 51, there is no such a structure arranged. Thus, claim 51 is not supported by the specification.

The specification is not in conformity with Rule 18 of the Implementing Regulation. Wording "surface sides" is unclear, does not clearly define its concrete position. In addition, "n-type" on page 10, line 21 (corresponding to page 31, ling 12 of the Japanese specification) of the specification should be amended to "p-type".

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Based on the above reasons, a patent right cannot be granted to the present application. If the applicant cannot provide sufficient reasons to show the claims possess novelty and inventiveness within the specified time limit, and cannot amend the application documents according to the examination comments to overcome the defects, the present application shall be finally rejected.



# 中华人民共和国国家知识产权局

邮政编码: 100037 北京市阜成门外大街 2 号万通新世界广场 8 层 中国国际贸易促进委员会专利商标事务所 王以平	が開発して
申请号:011457872	一种智慧
申请人: 佳能株式会社	图 1 3 3
发明创造名称,半导体器件及其制造方法和喷液设备	

## 第一次审查意见通知书

l,	. ②应申请人提出的实申请求,根据专利法第35条第1款的规定,国家知识产权局对上述发明专利申请进
	行实版审查。
	□根据专利法第 35 条第 2 款的规定, 国家知识产权局决定自行对上述发明专利申请进行审查。
2.	②中销人要求以其在:
	JI' 专利局的申请日 2000 年 12 月 28 日为优先权日,
	JP 专利局的申请日 2001年 02 月 09 日为优先权日,
	JP 专利局的中请日 2001年 02月 09 日为优先权日,
	JP 专利局的申请日 2001年 02月 09 日为优先权日,
	专利局的申请日 年 月 日为优先权日。
	☑申请人已经投交了经原申请国受理机关证明的第一次提出的在允申请文件的副本。
	□申请人尚未提交经原中请国受理机关证明的第一次提出的在先中请文件的副本,根据专利法第 30 条
	的规定视为未提出优先权要求。
3.	□ 经审查,申请人于·
٥.	
	年 月 日幾交的    不符合专利法第 33 条的规定, 年 月 日幾交的
1	中蛮针对的申请文件:
٦.	
	☑原始申请文件。 □审查是针对下述申请文件的
r.Jr	讲日ุ 设立的原始申请文件的权利要求第 项、说明书第 页、附图第 页;
	年 月 日提交的权利要求第 项、说明书第 页、附图第 页。
	年 月 日提交的权利要求第 项、说明书第 页、附图第 页。
	年 月 日提交的权利要求第 项、说明书第 页、附图第 页;
	年 月 日提交的说明书摘要, 年 月 日提交的摘要附图。
5,	□本通知书是在未进行检索的情况下作出的。
	☑本通知书是在进行了检索的情况下作出的。
	②本通知书引用下述对比文献(其编号在今后的审查过程中继续沿用):
	编号 文件号或名称 公开日期(或抵急申请的申请日)
	WALLEY CHANGE TO BE A PARTY
1	JI' 7 8-9741.0A 1996-4-1.2
2	Jじ平 6-69497A 1994-3-11
6.	p 查的结论性意见。
	☑关于说明书:
	ETV 1 RP M 14:

下榜 5 01145/0/2
□ 申稿的内容属于专利法第 5 条规定的不投予专利权的范围。
□ 申捐的内容属于专利法第 0 条规定的不仅下专利权的范围。 □ □ 记明书不符合专利法第 26 条第 3 款的规定。 □ □ □ □ □ □ 本不符合专利法第 33 条的规定。
第一 <b>区</b> 说明书的撰写不得合实施细则第 18 条的规定。
□ 权利要求
7. 【【权利要求1-6,10,113-16不具备专利法第22条第3款规定的创造性。
□权利要求 不具备专利法第22条第4款规定的实用性。
一段利要求·*** 属于专利法第 25 条规定的不授予专利权的范围。
VI 权利要求 51 不符合专利法第 26 条第 4 款的规定。
□权利要求 不符合专利法第 31 条第 1 款的规定。
□权利要求 不符合专利法第 33 条的规定。
□权利要求 不符合专利法实施组则第2条第1款关于发明的定义。
□权利娶求 不符合专利法实施组则第13条第1款的规定。
☑权利要求5,10,11,17-20,22~26,31-36,39,40不符合专利法实施细则第 20 条的规定。
<b>7</b> 权利要求 27 不符合专利法实施细则第 21 条的规定。
□权利要求 不符合专利法实施细则第22条的规定。
□权利要求 不符合专利法实施细则第 23 条的规定。
上述结论性意见的具体分析见本通知书的正文部分。
7. 基于上述结论性意见, 市查员认为:
□申请人应按照通知书正文部分提出的要求,对申请文件进行修改。
口中请人应在意见陈述书中论述其专利申请可以被授予专利权的理由,并对通知书正文部分中指出的不符
合规定之处进行修改, 否则将不能投予专利权。
□专利申请中没有可以被授予专利权的实质性内容,如果申请人没有陈述理由或者陈述理由不充分,其中
<b>讲将被驳回。</b>
8. 申请人应注意下述事项:
(1)根据专利法第37条的规定,中请人应在收到本通知书之门起的肆个月内陈述意见,如果中请人无正当理
由逾期不答复,其申请将被视为撤回。
(2)申请人对其申请的修改应符合专利法第33条的规定,修改文本应一式两份,其格式应符合审查指南的有
<del>关</del> 规定。
(3)申请人的意见陈述书和/或修改文本应邮寄或递交国家知识产权周专利局受理处,凡朱邮寄或递交给受理。
处的文件不具备法律效力。
(4)米经预约,申请人和/或代班人不得前来国家知识产权局专利局与审查员举行会晤。
9. 本通知书正文部分共有4页,并附有下述附件:
☑引用的对比文件的复印件共 <u>2</u> 份 <u>24</u> 页。□

甲查员: 钟翊(A113) 2004年9月9日



审查部门 电学发明审查部

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## 第1次审查意见通知书正文

如说明书所述,本申请涉及一种半导体器件及其制造方法和喷液设备。经 审查,现提出如下审查意见。

- 1、权利要求 1 不符合专利法实施细则第二十条第一款的规定。"表面侧"为不清楚的措辞,没有描述清楚该具体位置,造成权利要求的保护范围不清楚。"这些栅极之间设置有栅绝缘膜"没有描述消楚该绝缘膜是设置于多个栅电极彼此之间,还是设置于栅电极与沟道区之间,造成权利要求的保护范围不清楚,依据说明书的内容应修改为"这些栅极与沟道区之间设置有栅绝缘膜";权利要求 1 还没有描述清楚电热转换元件与转换器件的位置关系和连接方式,造成其要求保护的半导体器件的结构不清楚。
- 2、即便按照上述意见修改了权利要求 1,权利要求 1 仍然不符合专利法第二十二条第三款的规定。对比文件 1 (JP 平 897410A,说明书全文,附图 1-8)公开了一种横向 DMOS 的制造方法,包括:P型基板 12 上形成 N型半导体区 14,绝缘膜 28, 棚电极 26, P型半导体区 20, 形成在 P型半导体区的源区 16,形成在 N型半导体区中的漏区 18, P型半导体区位于多个漏区之间,对比文件 1 与权利要求 1 的区别在于:多个电热转换元件和多个转换器件集成在 P型衬底上,P型半导体区的杂质浓度高于 N型半导体区的杂质浓度。对比文件 2 (JP 平 6069497A,说明书全文,附图 1-22)公开了一种电热转换元件驱动半导体器件的结构,其中多个电热转换元件和多个转换器件集成在 P型衬底上;而将漏区的杂质浓度设为小于沟道区中的杂质浓度及/或漏的深度加深以使得晶体管的击穿电压变商是本领域用来提高晶体管的击穿电压的常用手段,属于公知常识,而对比文件 1 和对比文件 2 所属技术领域相同,将对比文件 1 中的晶体管结构结合公知常识应用了对比文件 2 的半导体装置中而得到权利要求 1 的技术方案对本领域技术人员来说是不需要创造性劳动的,因此权利要求 1 不具有创造性。
- 3、权利要求 2 不符合专利法第二十二条第三款的规定。对比文件 1 公开了权利要求 2 的附加技术特征(参见附图),因此权利要求 2 不具有创造性。
- 4、权利要求 3-6、10、13-16 不符合专利法第二十二条第三款的规定。对 比文件 1 和 2 公开了权利要求 3、5、6、10、13-16 的附加技术特征(参见附图),

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因此权利要求 3、5、6、10、13-16 不具有创造性, 电热转化元件可以与漏区迹 接是本领域常用的连接方式,属于公知常识,因此权利要求 4 不具有创造性。

- 5、权利要求 5 不符合专利法实施细则第二十条第一款的规定。"所述的 两个栅电极"在其引用的权利要求中没有出现过,造成权利要求的保护范围不 滑楚。
- 6、权利要求 10、11 不符合专利法实施细则第二十条第一款的规定。"... 的源一侧…"没有描述清楚该位置,造成权利要求的保护范围不清楚,应修改 为"...的靠近漏区的部分..."。
- 7、权利要求 17 不符合专利法实施细则第二十条第一款的规定。"...所述 漏侧…"在其所引用的权利要求中没有出现过,而且也没有描述清楚该所谓"漏 侧"的具体位置,造成权利要求的保护范围不清楚,可修改为"...靠近溺区的 部分..."; "比所述枷绝缘膜厚的绝缘膜"在其所引用的权利要求中没有出现 过,没有描述清楚该厚绝缘膜的具体位置,造成权利要求的保护范围不清楚。
- 8、权利要求 18-20 不符合变利法实施细则第二十条第一款的规定。"所 述结构是用...引入法杂质..."为不通顺不清楚的语句,造成权利要求的保护范 围不滑楚, "OFF 衬底"不是本领域常用的措辞,没有描述清楚该衬底的特征, 造成权利要求的保护范围不清楚,"...对应于...的排液部分"没有描述清楚该 "对应于"是如何连接的,其位置关系如何。
- 9、权利要求 22 不符合专利法实施细则第二十条第一款的规定。"表面侧" 为不清楚的措辞,没有描述清楚该具体位置,造成权利要求的保护范围不清楚。 "用所述棚电极作掩模掺杂第 1...杂质"没有描述清楚向哪一层的哪个位置掺 杂杂质,造成权利要求的保护范围不清楚,"通过扩散...形成...半导体区"没 有描述濟楚该半导体区形成的具体位置,造成权利要求的保护范围不清楚。
- 10、权利要求 23 不符合专利法实施细则第二十条第一款的规定。"表面 侧"为不清楚的措辞,没有描述濟楚该具体位置,造成权利要求的保护范围不 南楚: "用所述棚电极作掩模掺杂第 1...杂质"没有描述清楚向哪一层的哪个 位置掺杂杂质,造成权利要求的保护范围不清楚;"通过扩散...形成...半导体 区"没有描述滑楚该半导体区形成的具体位置,造成权利要求的保护范围不清 楚。
  - 11、权利要求 24 和 25 不符合专利法实施细则第二十条第一款的规定。"表

面侧"为不清楚的措辞,没有描述清楚该具体位置,造成权利要求的保护范围 不清楚: "100kev 以上"为不清楚的指辞,没有限定清楚该能量的范围,造成 权利要求的保护范围不滑楚,"进行热处理,以电...杂质"中的该杂质与"... 进行第 1 导电类型离子注入"之间的关系不清楚,造成权利要求的保护范围不 清楚,应将"…进行第1导电类型离子注入"修改为"…进行第1导电类型杂 质离子注入"。

- 12、权利要求 26 不符合专利法实施细则第二十条第四款的规定。括号中 的内容是不允许的,应当删除。
- 13、权利要求 27 不符合专利法实施细则第二十一条第三款的规定。权利 要求 27 是对权利要求 22 的进一步限定,应作为其从属权利要求。
- 14、权利要求 31-34 不符合专利法实施细则第二十条第一款的规定。"OFF 衬底"不是本领域常用的措辞,没有描述清楚该衬底的特征,造成权利要求的 保护范围不清楚, "100kcv 以上"为不清楚的措辞,没有限定清楚该能量的范 圈,造成权利要求的保护范围不清楚。
- 15、权利要求 35 不符合专利法实施细则第二十条第一款的规定。"所述等 两个栅电极"与"所述的两个栅电极"在前面没有出现过,因此没有描述清楚 该两个棚电极为哪个位置关系的栅电极,造成权利要求的保护范围不清楚:"对 两个相邻的所述栅电极之间进行离子注入,其后...第 1 导电类型杂质,形成第 1...的第2半导体区"没有描述清楚进行的是什么类型的离子注入,而其后扩散 的第 1 导电类型的杂质在前面没有出现过,且没有描述滑楚其与前面进行的离 子注入是什么关系,此外,没有描述滑楚第 2 半导体区形成在整个结构中的哪 个位置哪一层哪一区,造成权利要求的保护范围不清楚。
- 16、权利要求 36 不符合专利法实施细则第二十条第一款的规定。"所述 两个栅电极"与"所述的两个栅电极"在前面没有出现过,因此没有描述清楚 该两个栅电极为哪个位置关系的栅电极,造成权利要求的保护范围不清楚,"在 两个所述栅电极之间注入杂质,其后...第 1 导电类型杂质,形成第 1...的第 2 半导体区"没有描述清楚注入的是什么类型的杂质,而其后扩散的第 1 导电类 型的杂质在前面没有出现过,且没有描述清楚其与前面进行的杂质注入是什么 关系,此外,没有描述消楚第 2 半导体区形成在整个结构中的哪个位置哪一层 哪一区,造成权利要求的保护范围不清楚。

17、权利要求 39 不符合专利法实施细则第二十条第一款的规定。"按垂 直于所述半导体衬底...杂质离子注入后,通过扩散第 1 导电类型杂质,形成第 2 半导体区"没有描述清楚注入的是什么类型的杂质,而其后扩散的第 1 导电 类型的杂质在前面没有出现过,且没有描述消楚其与前面进行的杂质注入是什 么关系,此外,没有描述清楚第 2 半导体区形成在整个结构中的哪个位置哪一 层哪一区,造成权利要求的保护范围不清楚。

18、权利要求 40 不符合专利法实施细则第二十条第一款的规定。"按垂 直方向向所述半导体衬底...杂质离子注入后,通过扩散第 1 导电类型杂质,形 成第 2 半导体区"没有描述清楚该垂直方向是相对于哪个位置的垂直方向:注 入的是什么类型的杂质,而其后扩散的第1导电类型的杂质在前面没有出现过, 且没有描述滴楚其与前而进行的杂质注入是什么关系,此外,没有描述清楚第 2 半导体区形成在整个结构中的哪个位置哪一层哪一区, 造成权利要求的保护 范围不滑楚.

19、权利要求 51 不符合专利法第二十六条第四款的规定,如说明书第 17 页第 3 段的内容以及说明书各实施例中的内容可知,必须使第 2 半导体区的底 部有足够的深度与接地的半导体衬底相接,使第 2 半导体区到达衬底,以确保 每个漏可以在电学上独立地被隔开,不是这样的结构不适用于喷液设备用的品 体管阵列, 而权利要求 51 所引用的权利要求 1 和 2 所要求保护的结构中, 没有 设置这样的一种结构、因此没有以说明书为依据。

说明书不符合专利法实施细则第十八条的规定。"表面侧"为不清楚的措 辞,没有描述潸楚该具体位置;说明书第 10 页第 21 行"N型"应修改为"P 型"。

基于上述理由,本发明申请不能被授予专利权。如果申请人不能在规定的 期限内除述权利要求具有新颖性和创造性的充分理由,并按照本通知书的意见 修改中请文本,克服所存在的缺陷,本中谓将被驳回。